



60V 175°C DUAL N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _C = +25°C
60V	11mΩ @ V _{GS} = 10V	47.6A
607	16mΩ @ V _{GS} = 4.5V	39.5A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

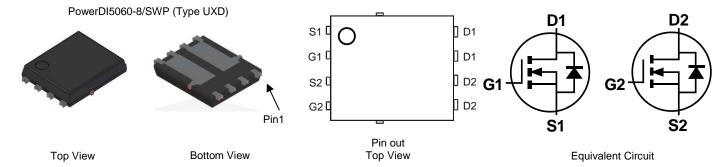
- Engine management systems
- Body control electronics
- DC-DC converters

Features and Benefits

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMTH6010LPDWQ)

Mechanical Data

- Package: PowerDI[®]5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)



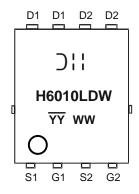
Ordering Information (Note 4)

Part Number	Backago	Packing		
Fait Number	Package	Qty.	Carrier	
DMTH6010LPDW-13	PowerDI5060-8/SWP (Type UXD)	2,500	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



⊃¦¦ = Manufacturer's Marking
 H6010LDW = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 22 = 2022)
 WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	60	V	
Gate-Source Voltage		Vgss	±20	V
Continuous Drain Current (Note 6) $ T_C = +25^{\circ}C $ $ T_C = +100^{\circ}C $		ID	47.6 33.7	А
Continuous Drain Current (Note 5) $ T_{A} = +25^{\circ}C $ $ T_{A} = +70^{\circ}C $		lo	13.1 10.9	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	90	А	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	31	A	
Avalanche Current, L = 0.1mH		las	20	A
Avalanche Energy, L = 0.1mH		Eas	20	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	2.8	W
Thermal Resistance, Junction to Ambient (Note 5)	RθJA	53	°C/W
Total Power Dissipation (Note 6)	PD	37.5	W
Thermal Resistance, Junction to Case (Note 6)	Rejc	4	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

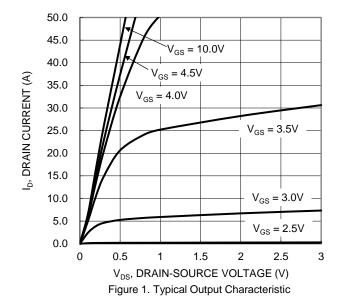
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)			1 - 71-				
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	VGS = 0V, ID = 1mA	
Zero Gate Voltage Drain Current	IDSS	_	<u> </u>	1	μΑ	V _{DS} = 48V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)			.1		.1		
Gate Threshold Voltage	Vgs(TH)	1	_	3	V	V _{DS} = V _{GS} , I _D = 250μA	
Static Drain-Source On-Resistance	Decrey	_	8.5	11	mΩ	Vgs = 10V, ID = 20A	
Static Diam-Source On-Resistance	RDS(ON)	_	10.9	16	11122	V _{GS} = 4.5V, I _D = 20A	
Diode Forward Voltage	VsD	_	0.9	1.2	V	V _G S = 0V, I _S = 20A	
DYNAMIC CHARACTERISTICS (Note 8)				<u> </u>	·		
Input Capacitance	Ciss	_	2615	_	pF		
Output Capacitance	Coss	_	1415		pF	$V_{DS} = 30V$, $V_{GS} = 0V$, f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	58	_	pF		
Gate Resistance	Rg	_	0.67	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (Vgs = 4.5V)	Qg	_	20.3	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	40.2	_	nC	T.,	
Gate-Source Charge	Qgs	_	5.9	_	nC	$V_{DS} = 30V, I_D = 20A$	
Gate-Drain Charge	Q _{gd}	_	9.3	_	nC	7	
Turn-On Delay Time	t _D (ON)	_	5.7	_	ns		
Turn-On Rise Time	t _R	_	8.8	_	ns	V _{DD} = 30V, V _{GS} = 10V,	
Turn-Off Delay Time	t _{D(OFF)}	_	20.8	_	ns	$I_D = 20A$, $R_G = 3\Omega$	
Turn-Off Fall Time	tF	_	7.4	_	ns	7	
Body Diode Reverse Recovery Time	t _{RR}	_	34.5	_	ns	1 00A 11/11 400A/1	
Body Diode Reverse Recovery Charge	QrR	_	37.5	_	nC	I _F = 20A, di/dt = 100A/μs	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

^{5.} Device involved on the state of the state of







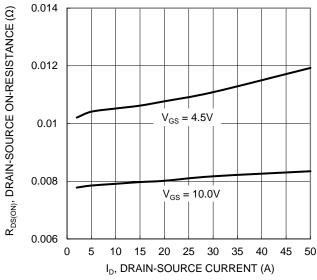


Figure 3. Typical On-Resistance vs Drain Current and Gate Voltage

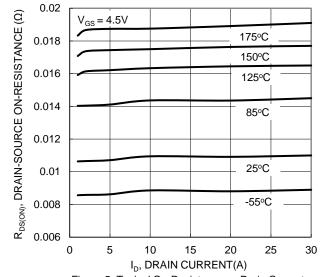
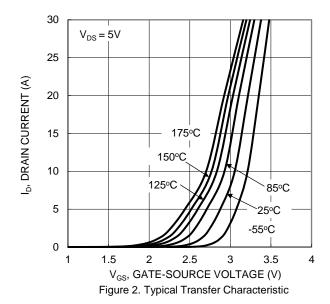
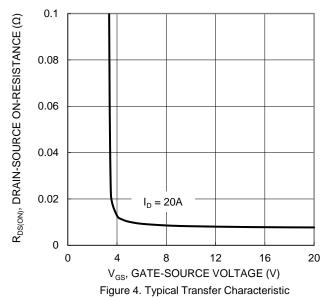


Figure 5. Typical On-Resistance vs Drain Current and Junction Temperature





1.8 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE $V_{GS} = 10V, I_{D} = 20A$ 1.6 (NORMALIZED) 1.2 $V_{GS} = 4.5 V, I_{D}$ = 20A1 0.8 0.6 -50 0 25 50 75 100 125 150 175 T_J, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Junction Temperature





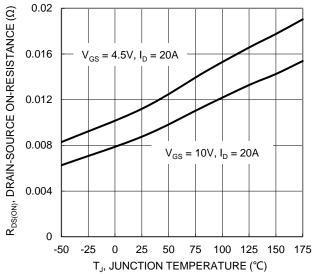


Figure 7. On-Resistance Variation with Junction Temperature

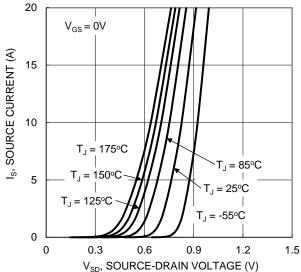


Figure 9. Diode Forward Voltage vs Current

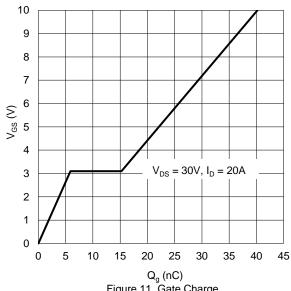


Figure 11. Gate Charge

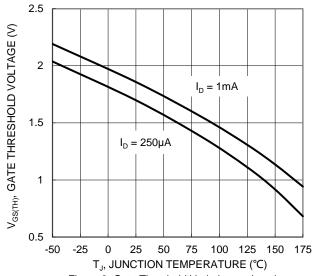


Figure 8. Gate Threshold Variation vs Junction Temperature

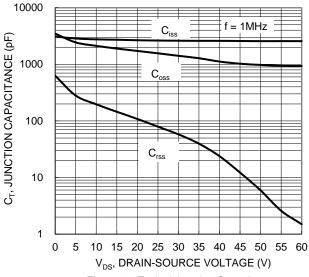


Figure 10. Typical Junction Capacitance

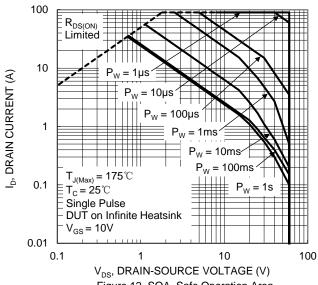


Figure 12. SOA, Safe Operation Area



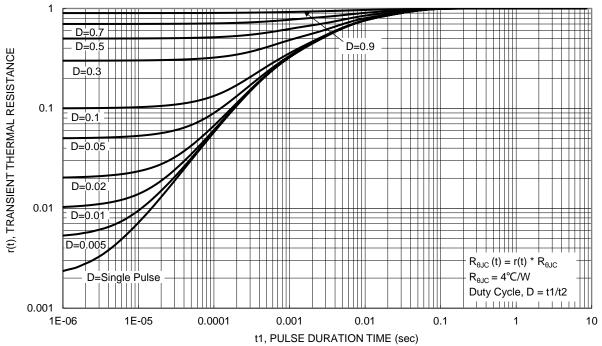


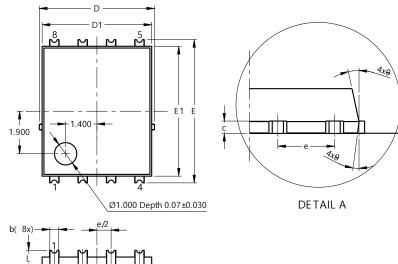
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

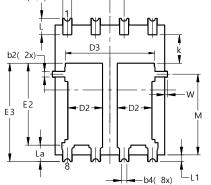
Please see http://www.diodes.com/package-outlines.html for the latest version.

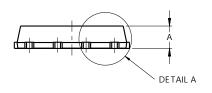
PowerDI5060-8/SWP (Type UXD)



PowerDI5060-8/SWP					
(Type UXD)					
Dim	Min	in Max Typ			
Α	0.90	1.10	1.00		
A1	0.00	0.05			
b	0.30	0.50	0.41		
b2	0.20	0.35	0.25		
b4	().25REF			
С	0.230	0.330	0.277		
D	5	.15 BS0)		
D1	4.70	5.10	4.90		
D2	1.46	1.66	1.55		
D3			3.98		
Е	6.40 BSC				
E1	5.60	6.00	5.80		
E2	3.46	3.86	3.66		
E2a	4.195	4.595	4.395		
е	1.27BSC				
k	1.05				
L	0.635	0.835	0.735		
La	0.635	0.835	0.735		
L1	0.200	0.400	0.300		
M	3.205	4.005	3.605		
W	0.025	0.225	0.125		
θ	10°	10° 12° 11			
θ1	6° 8° 7°		7°		
All	All Dimensions in mm				

Seating Plane

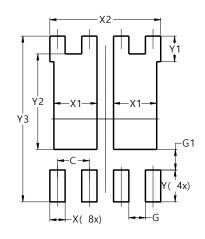




Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8/SWP (Type UXD)



Dimensions	Value (in mm)		
C	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	1.720		
X2	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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